- State-of-the-Art *EPIC-*II*B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT240, SN74ABT240A, SN54ABT241, and SN74ABT241A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs.

SN54ABT244 J OR W PACKAGE
SN74ABT244A DB, DW, N, OR PW PACKAGE
(TOP VIEW)

	,	
1 2 3 4 5 6 7 8 9	15 14 13] V _{CC}] 2OE] 1Y1] 2A4] 1Y2] 2A3] 1Y3] 2A2] 1Y4
o 9] 2A2
10	11] 2A1
	3 4 5 6 7 8 9	2 19 3 18 4 17 5 16 6 15 7 14 8 13 9 12

SN54ABT244 . . . FK PACKAGE (TOP VIEW)

	2Y4 1A1 1 <u>OE</u> V _{CC}	
	/	1
1A2	3 2 1 20 19] 4 18[] 5 17[1Y1
1A2 2Y3	5 17	2A4
1A3 2Y2 1A4	6 16	1Y2
2Y2	7 15	2A3 1Y3
1A4	8	1Y3
	9 10 11 12 13	
		J
	2Y1 GND 2A1 1Y4 2A2	
	ているりる	

The SN54ABT244 and SN74ABT244A are organized as two 4-bit buffers/line drivers with separate \overline{OE} inputs. When \overline{OE} is low, the devices pass noninverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT244 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT244A is characterized for operation from -40° C to 85° C.



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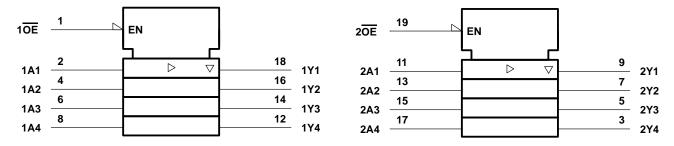


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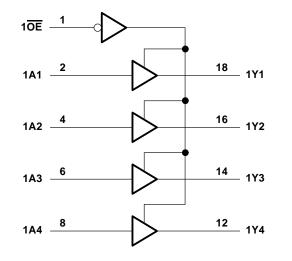
FUNCTION TABLE (each buffer)									
INP	JTS	OUTPUT							
OE	Α	Y							
L	Н	Н							
L	L	L							
Н	Х	Z							

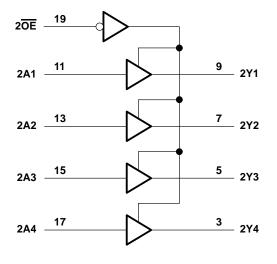
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)







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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) Voltage range applied to any output in the high Current into any output in the low state, I _O : SN	or power-off state, V _O	
		128 mA
Input clamp current, I _{IK} (V _I < 0)		
Output clamp current, I_{OK} (V _O < 0)		
Package thermal impedance, θ_{JA} (see Note 2)		
	N package	
	PW package	128°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT24			4 SN74ABT244A		
					MIN	MAX	UNIT	
V _{CC}	Supply voltage		4.5	5.5	4.5	5.5	V	
VIH High-level input voltage			2		2		V	
VIL	VIL Low-level input voltage			0.8		0.8	V	
VI Input voltage			0	VCC	0	VCC	V	
ЮН	High-level output current			-24		-32	mA	
IOL Low-level output current			48		64	mA		
$\Delta t/\Delta v$	Input transition rise or fall rate	tion rise or fall rate Outputs enabled		5		5	ns/V	
T _A Operating free-air temperature		-55	125	-40	85	°C		

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	METED	TEST CO		Т		;	SN54A	BT244	SN74AB	T244A	UNIT	
PARA	METER	TEST COI	NDITIONS	MIN	MIN TYP [†] MAX MIN MAX		MIN	MIN MAX				
VIK		V _{CC} = 4.5 V,	lı = –18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
V		V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2					
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			v	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
Ц		V _{CC} = 5.5 V,	$V_I = V_{CC} \text{ or } GND$			±1		±1		±1	μΑ	
IOZH		V _{CC} = 5.5 V,	V _O = 2.7 V			10		10		10	μΑ	
IOZL		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-10		-10		-10	μΑ	
loff		$V_{CC} = 0,$	V _I or V _O \leq 4.5 V			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V	Outputs high			50		50		50	μΑ	
10‡		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
			Outputs high		1	250		250		250	μA	
ICC		$V_{CC} = 5.5 \text{ V}, I_O = 0,$ $V_I = V_{CC} \text{ or GND}$	Outputs low		24	30		30		30	mA	
	_		Outputs disabled		0.5	250		250		250	μA	
	Data	$V_{CC} = 5.5 V$, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5		
∆ICC§	inputs	Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	$V_{CC} = 5.5 V$, One input Other inputs at V_{CC} or C				1.5		1.5		1.5	5	
Ci		V _I = 2.5 V or 0.5 V			3.5						pF	
Co		V _O = 2.5 V or 0.5 V			7.5						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5$ V.

[‡]Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

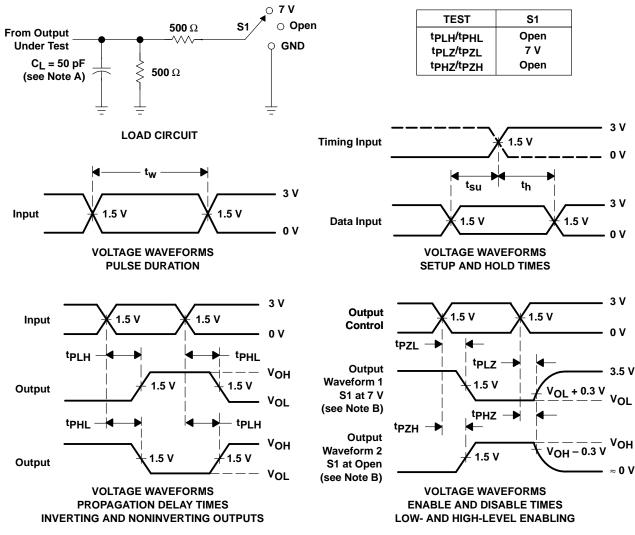
PARAMETER				SN	54ABT2	44		
	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	МАХ	UNIT
			MIN	TYP	MAX			
t _{PLH}	A	v	1	2.6	4.1	1	5.3	ns
^t PHL		I	1	2.9	4.2	1	5	115
^t PZH	ŌĒ	V	1.1	3.1	4.6	0.8	5.7	ns
^t PZL		I	2.1	4.1	5.6	1.2	7.9	115
^t PHZ	OE	×	2.1	4.1	5.6	1.2	7.6	ns
^t PLZ	UE	1	1.5	3.7	5.6	1	7.9	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

				SN7	4ABT24	4A		
PARAMETER FROM TO (INPUT) (OUTPUT)		-	Vo T	CC = 5 V 4 = 25°C	l, ;;	MIN	МАХ	UNIT
	MIN	TYP	MAX					
^t PLH	A	v	1	2.6	4.1	1	4.6	ns
^t PHL			1	2.9	4.3	1	4.6	115
^t PZH		v	1.1	3.1	4.6	1.1	5.1	ns
^t PZL	ŌĒ		2.1	4.1	5.6	2.1	6.1	115
^t PHZ	OE	v	1.8	4.1	5.6	1.8	6.6	ns
^t PLZ	UE		1.4	3.7	5.2	1.4	5.7	115



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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